HL1513AF

1.55 µm 10Gb/s Laser Diode with EA Modulator

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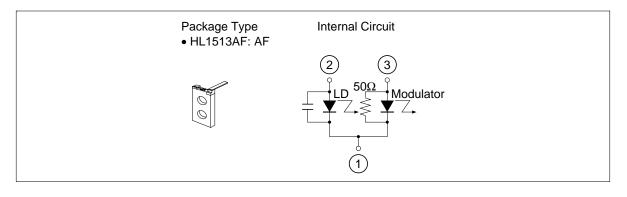
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Description

The HL1513AF is a 1.55 μ m InGaAsP distributed-feedback laser diode (DFB-LD) with a multi-quantum well (MQW) structure. An electro-absorption (EA) modulator is integrated with the laser diode. It is suitable as a light source for 10 Gb/s WDM systems up to 40 km.

Features

- Wide wavelength coverage: $\lambda p = 1527$ to 1565 nm (C-BAND)
- High extinction ratio: 10 dB Min under modulated
- Dynamic single longitudinal mode: Sr = 40 dB Typ
- Package: open air package (chip on carrier) with micro strip-line





HL1513AF

Absolute Maximum Ratings $(T_C = 25^{\circ}C)$

Item	Symbol	Value	Unit	
LD forward current	I _F	100	mA	
Laser diode reverse voltage	$V_{R(LD)}$	2	V	
Modulator forword voltage	$V_{F(EA)}$	1	V	
Modulator reverse voltage	$V_{R(EA)}$	5	V	
Operating temperature	Topr	+15 to +30	°C	
Storage temperature *	Tstg	-40 to +85	°C	

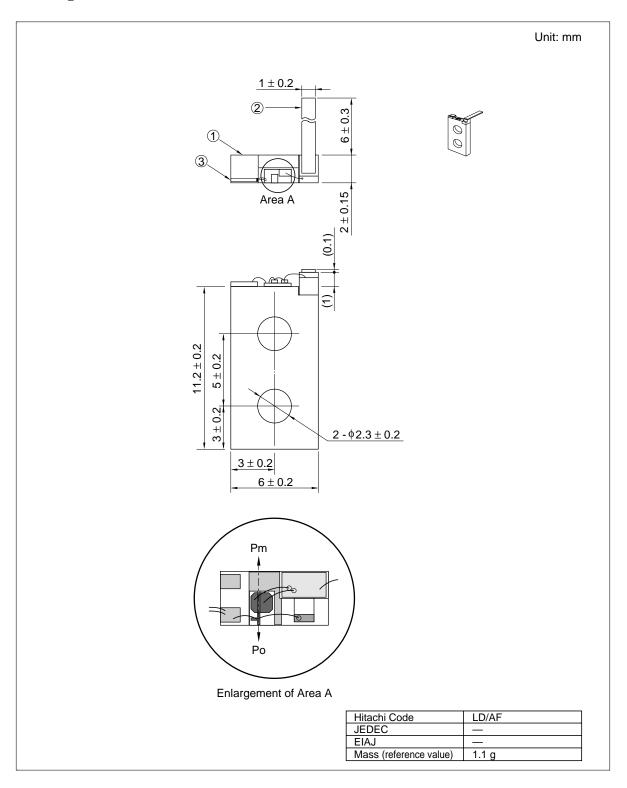
Note: without condensation

Optical and Electrical Characteristics ($T_C = 25$ °C)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Threshold current	lth	_	_	25	mA	
Optical output power	Po	2	_		dBm	I _{F(LD)} = 60 mA, Modulated *
Extinction ratio	ER	10	_		dB	I _{F(LD)} = 60 mA, Modulated *
Lasing wavelength	λр	1527	1550	1565	nm	I _{F(LD)} = 60 mA, Modulated *
Side-mode suppression ratio	Sr	35	_		dB	I _{F(LD)} = 60 mA, Modulated *
Transmission dispersion penalty	Pd	_	_	2	dB	$I_{F(LD)} = 60 \text{ mA}, \text{ Modulated *}, 750 \text{ ps/nm}$
Cutoff frequency	S ₂₁	12	_		GHz	$I_{F(LD)} = 60 \text{ mA}, V_{R(EA)} = -1 \text{ V}$
RF return loss	S ₁₁	8	_	_	dB	0.13 to 5 GHz
		5	_	_	dB	5 GHz to 10 GHz

Note: 9.95328 Gb/s, NRZ, V offset = 0 to -1 V, V mod = 2.5 Vpp max

Package Dimensions



HL1513AF

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